1. Scope:

1-1. This specification applies to N channel silicon MOSFET chips, Device no. PM-0117A

2. Structure:

2-1. Planar type.

2-2. Electrodes.

Source : Aluminum alloy . Gate : Aluminum alloy . Drain : Gold alloy.

3. Size:

3-1. Chip size: 46.9 mils ×46.9 mils (1.190 mm ×1.190 mm).

3-2. Chip thickness: 12 ±1.5mils (0.305± 0.038mm).

3-3. Pad size:

Source : 12.0 mils \times 10.0 mils (0.306 mm \times 0.256mm). Gate : 5.9 mils \times 5.9 mils (0.150mm \times 0.150 mm).

3-4. Pattern drawing: Refer to the attached drawing.

4. Absolute maximum rating (Ta = 25 $^{\circ}$ C)

Parameter	Symbol	Rating	Unit
Continuous drain current V _{GS} =5v	I _{D(m)}	0.4	Α
Drain-source Voltage	V_{DSS}	250	V
Gate-source Voltage	V_{GS}	±10	V
Operating junction and storage temperature range	Tj T _{STG}	-40to+150	$^{\circ}\!\mathbb{C}$

5. Electrical characteristics (Ta = $25 \,^{\circ}$ C)

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Drain to source breakdown voltage	BV _{DSS}	VGS = 0 V I _D = 100 uA	250			V
Gate threshold voltage	$V_{GS(th)}$	V _{DS} = V _{GS} I _D =1mA	1.0	1.8	3.0	٧
Gate to source leakage current	I _{GSS}	$V_{GS} = \pm 10V$ $V_{DS} = 0V$		± 0.07	± 1	μА
Drain to source leakage current	I _{DSS}	$V_{GS} = 0V$ $V_{DS} = 250V$			1	μА
Drain to source on resistance	R _{DS(on)}	$V_{GS} = 5V$ ID = 100mA		4	4.5	Ω
Diode forward voltage drop	V_{SD}	VGS = 0V ISD = 100mA		0.84	1.8	٧

Pattern drawing





